



ALPHA & OMEGA
SEMICONDUCTOR



AO4821

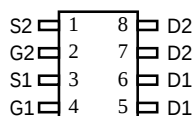
Dual P-Channel Enhancement Mode Field Effect Transistor

General Description

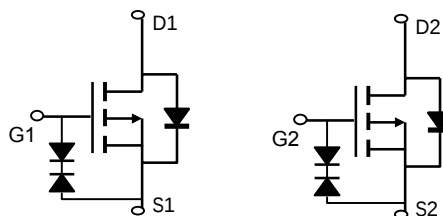
The AO4821 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected. *Standard Product AO4821 is Pb-free (meets ROHS & Sony 259 specifications). AO4821L is a Green Product ordering option. AO4821 and AO4821L are electrically*

Features

V_{DS} (V) = -12V
 I_D = -8 A (V_{GS} = -4.5V)
 $R_{DS(ON)} < 18m\Omega$ (V_{GS} = -4.5V)
 $R_{DS(ON)} < 22m\Omega$ (V_{GS} = -2.5V)
 $R_{DS(ON)} < 29m\Omega$ (V_{GS} = -1.8V)
ESD Rating: 4KV HBM



SOIC-8



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-12	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ^A	I_D	-8	A
	$T_A=70^\circ\text{C}$	-6.7	
Pulsed Drain Current ^B	I_{DM}	-20	
Power Dissipation ^A	P_D	2	W
	$T_A=70^\circ\text{C}$	1.28	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	48	62.5	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A		74	110	$^\circ\text{C/W}$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	35	40	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-12			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-9.6\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^{\circ}\text{C}$			-1 -5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 4.5\text{V}$			± 1	μA
		$V_{DS}=0\text{V}$, $V_{GS}=\pm 8\text{V}$			± 10	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.3	-0.55	-1	
$I_{D(ON)}$	On state drain current	$V_{GS}=-4.5\text{V}$, $V_{DS}=-5\text{V}$	-20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}$, $I_D=-8\text{A}$ $T_J=125^{\circ}\text{C}$		14.8 19	18 23	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$, $I_D=-8\text{A}$		18.3	22	$\text{m}\Omega$
		$V_{GS}=-1.8\text{V}$, $I_D=-5\text{A}$		22.4	29	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-8\text{A}$		34		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.74	-1	V
I_S	Maximum Body-Diode Continuous Current				-2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-6\text{V}$, $f=1\text{MHz}$		3960		pF
C_{oss}	Output Capacitance			910		pF
C_{rss}	Reverse Transfer Capacitance			757		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		6.9		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-4.5\text{V}$, $V_{DS}=-6\text{V}$, $I_D=-8\text{A}$		37		nC
Q_{gs}	Gate Source Charge			4.4		nC
Q_{gd}	Gate Drain Charge			11		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=-4.5\text{V}$, $V_{DS}=-6\text{V}$, $R_L=0.75\Omega$, $R_{GEN}=3\Omega$		15		ns
t_r	Turn-On Rise Time			43		ns
$t_{D(off)}$	Turn-Off Delay Time			158		ns
t_f	Turn-Off Fall Time			95		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-8\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		63		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-8\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		56		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $\leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

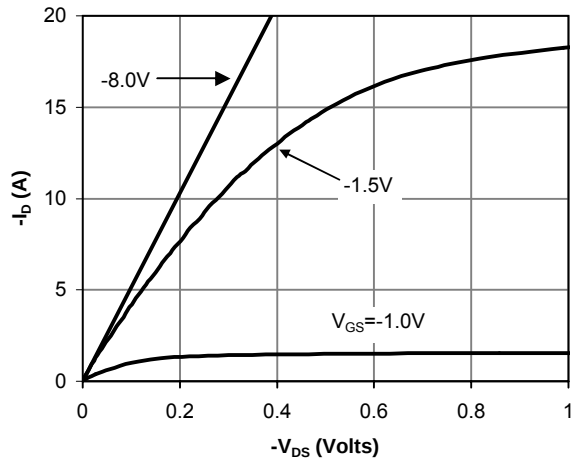


Fig 1: On-Region Characteristics

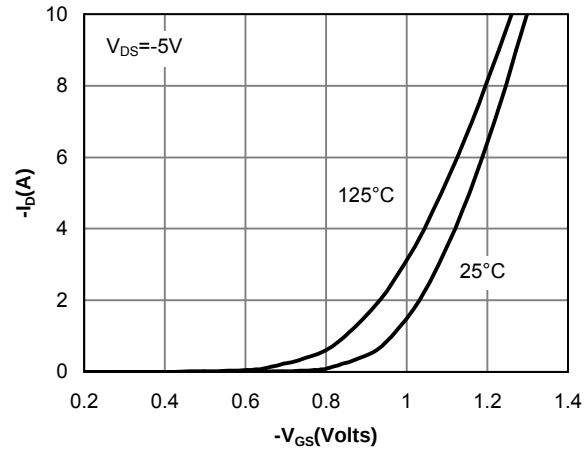


Figure 2: Transfer Characteristics

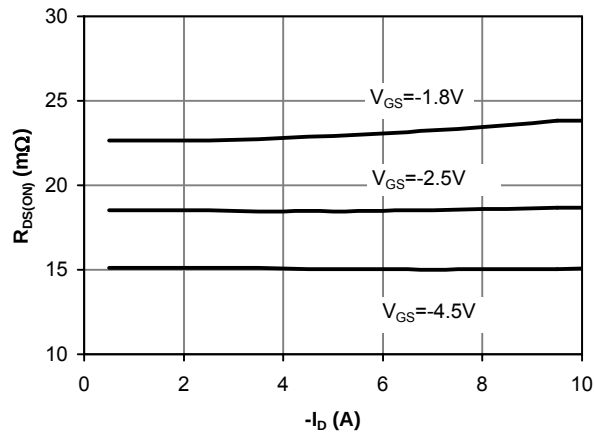


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

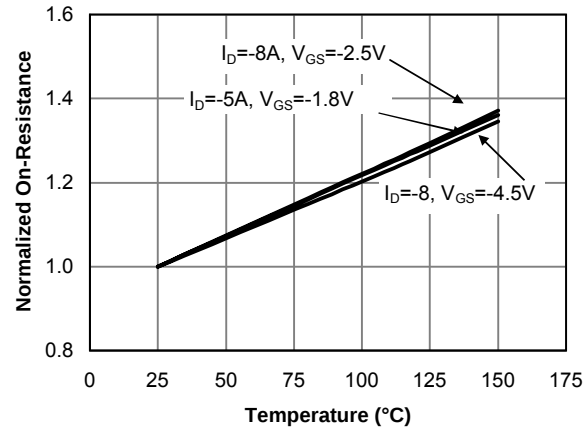


Figure 4: On-Resistance vs. Junction Temperature

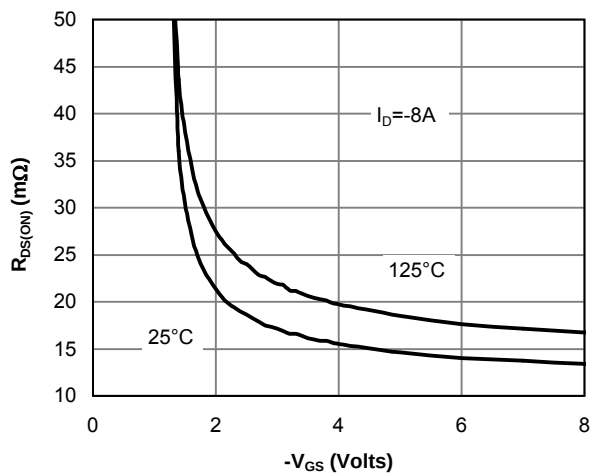


Figure 5: On-Resistance vs. Gate-Source Voltage

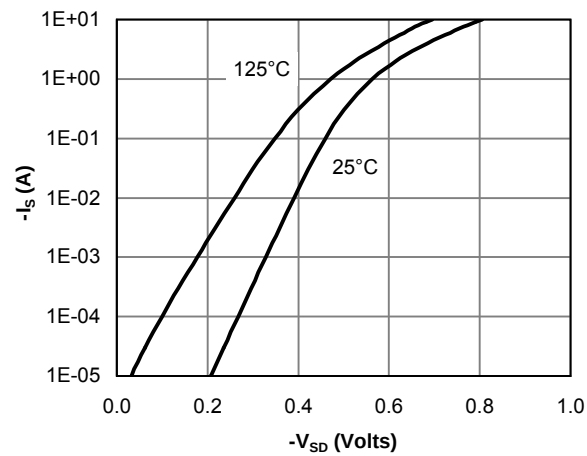


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

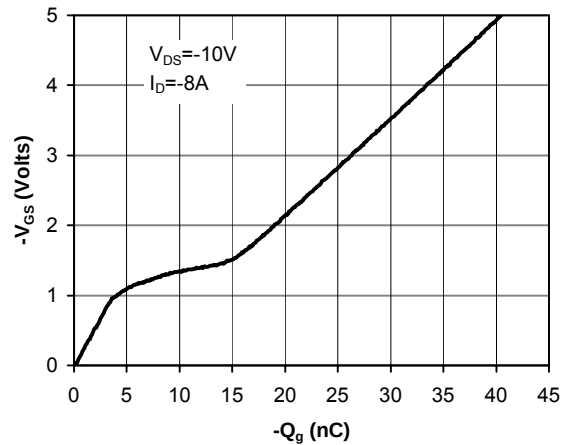


Figure 7: Gate-Charge Characteristics

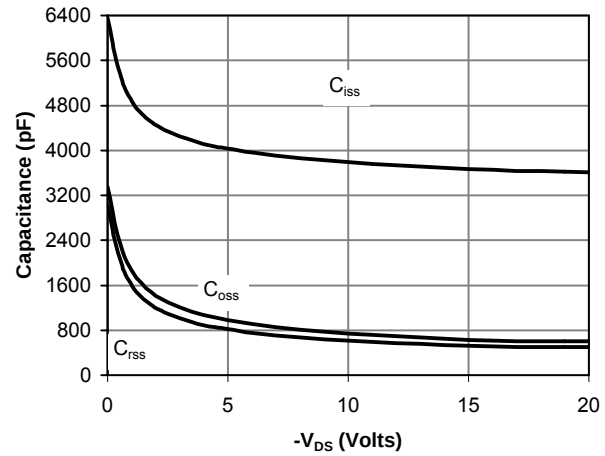


Figure 8: Capacitance Characteristics

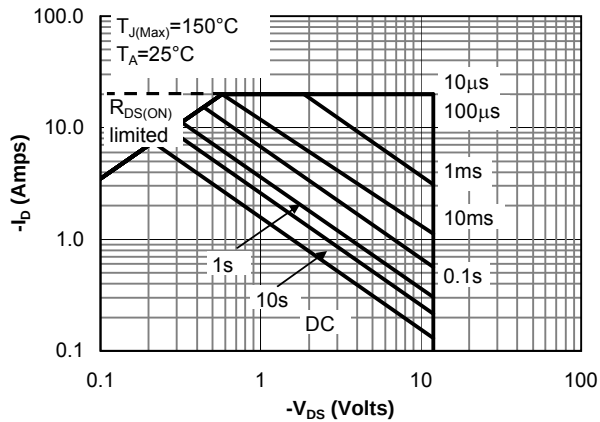


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

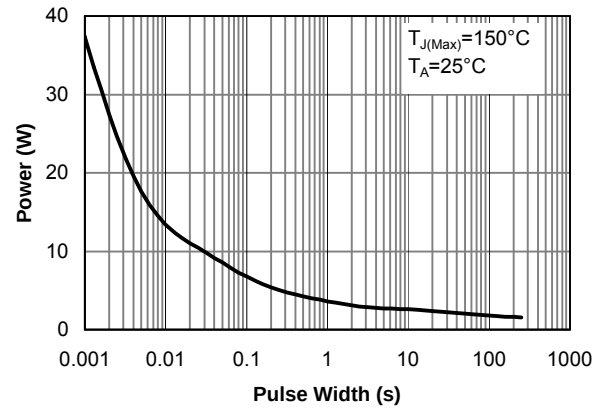


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

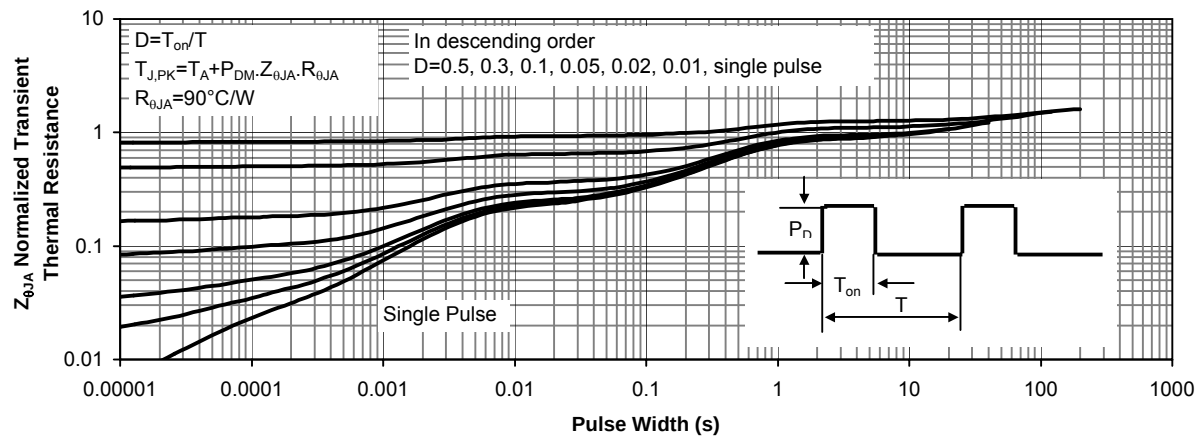


Figure 11: Normalized Maximum Transient Thermal Impedance